Electronic Supplementary Material (ESI) for Green Chemistry.

Electronic supplementary information

Fully atom-efficiency transformation of wasted polycarbonate into

epoxy thermosets and the catalyst-free degradation of the thermosets

for environmental sustainability

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Fig. S1. IR spectra of (a) base-soaked CD-PC, (b) acid-soaked CD-PC, (c) sandpapergrinded CD-PC, and (d) fresh PC.



Fig. S2. ¹H-NMR spectra of (a) based-soaked CD-PC and (b) fresh PC in dchloroform



Fig S3. GPC curves of (a) base-soaked CD-PC, (b) acid-soaked CD-PC, (c) sandpaper-grinded CD-PC, and (d) fresh PC. NMP was used as the mobile phase.



Fig. S4. ¹H-NMR spectra of the reaction product of DPC and GPE at different stages, including 120 °C for 2h, 140 °C for 2h, and 160 °C for 2h, respectively.



Fig. S5. ¹H-NMR spectra for the reaction of DPC and GPE after reacting at 120 °C for different periods of time.



Fig. S6. ¹H-NMR spectra of DPC with DMAP before and after stirring at 120 °C for







DMAP) that has been stirred at 200 °C for 1h.



Fig. S8. ¹H-NMR spectra of (a) WPC, (b) epoxy IV, and (c) WPC/IV blend (without



DMAP) that has been stirred at 200 °C for 1h.

Fig. S9. ¹H-NMR spectra of the reaction product of ethyl benzoate and GPE with 0.5wt% of DMAP at 120 °C for different periods of time.



Fig. S10. ¹H-NMR spectra of the reaction product of acetophenone and GPE with 0.5wt% of DMAP at 120 °C for different periods of time.



Fig. S11. The relation of $1/T_g$ and epoxy equivalent weight (EEW)



Scheme S1. The simplified curing chemistry of WPC and epoxy I.